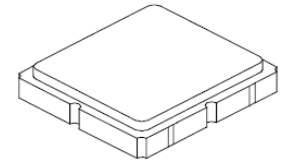


SF2202E

**2017.5 MHz
SAW Filter**



SM3030-6

- **Surface Mount 3.0 x 3.0 x 1.3 mm Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-30 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F_C			2017.5		MHz
Insertion Loss, 2010 to 2025 MHz	IL			2.9	4.0	dB
Amplitude Ripple, 2010 to 2025 MHz				0.5	1.5	dB
VSWR, 2010 to 2025 MHz				2.0	2.5	
Group Delay Ripple, 2010 to 2025 MHz				4.0	25	ns
Attenuation, Referenced to 0 dB						
D.C. to 1200 MHz			40	48		dB
1200 to 1860 MHz			33	38		
1920 to 1980 MHz			13	28		
2045 to 2070 MHz			6	17		
2070 to 2085 MHz			26	39		
2085 to 2800 MHz			30	35		
2800 to 4000 MHz			22	30		
Source Impedance	Z_S			50		Ω
Load Impedance	Z_L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	932, <u>YWWS</u>					

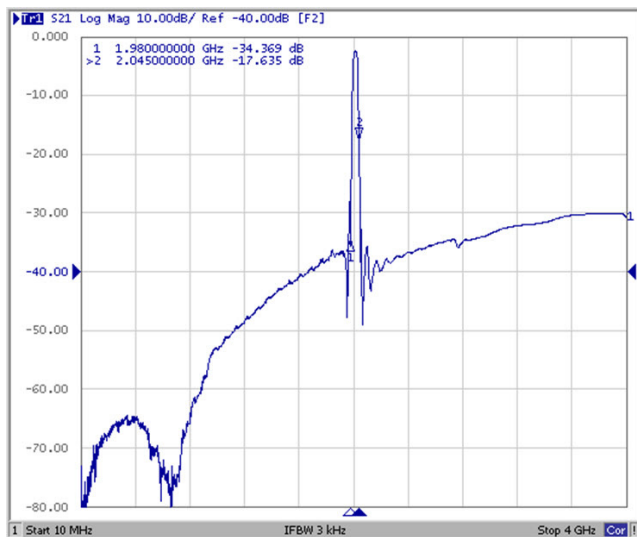
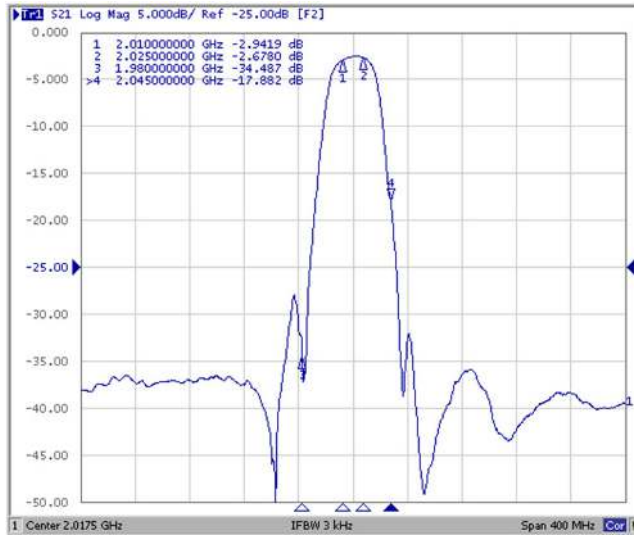
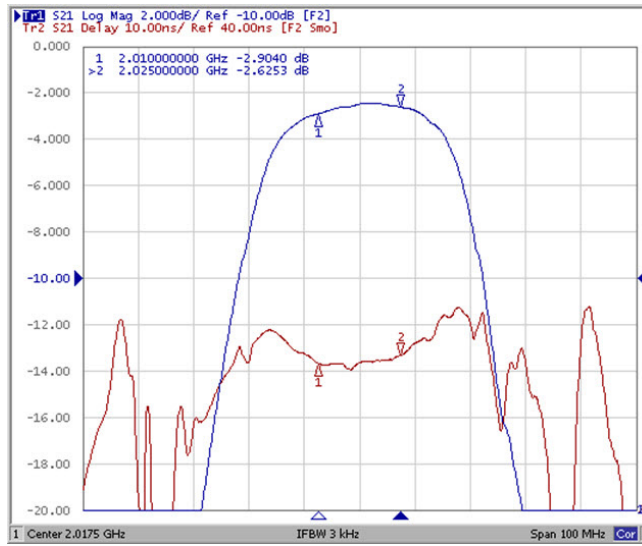


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

NOTES:

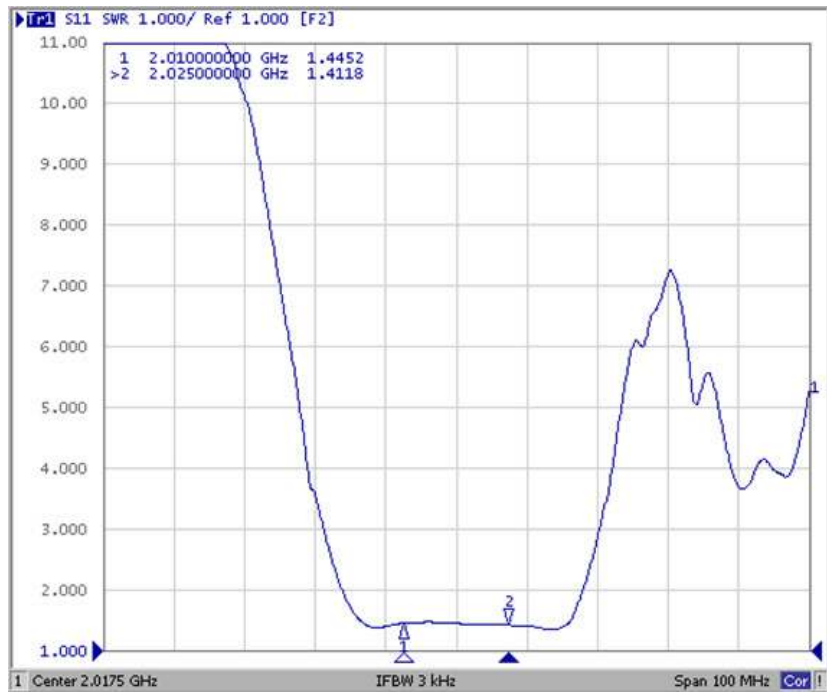
1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Frequency Characteristics

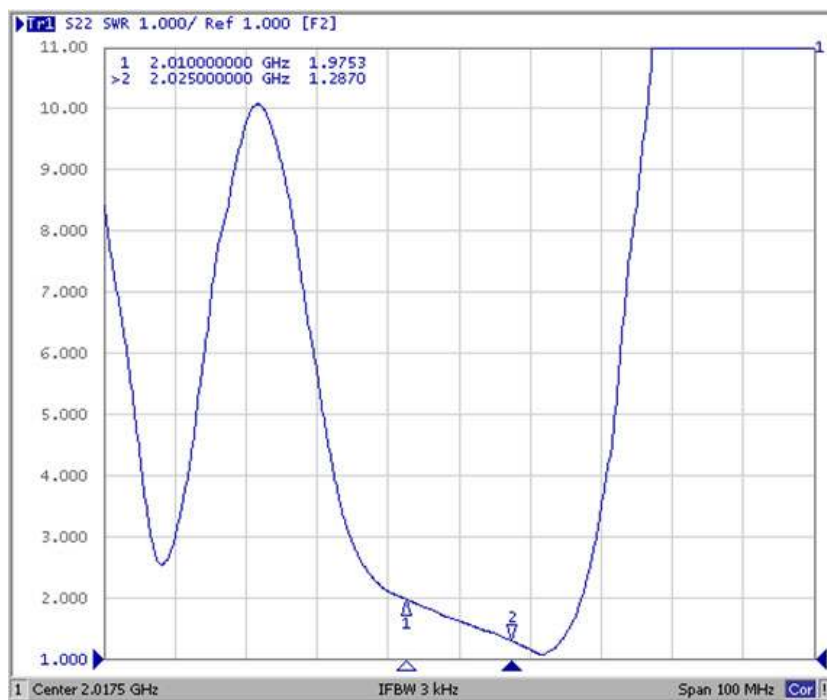


Reflection Functions

S11

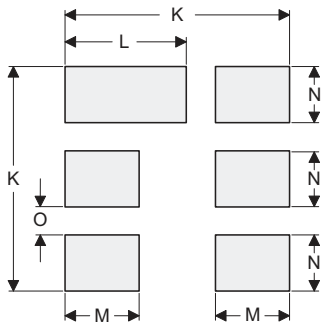
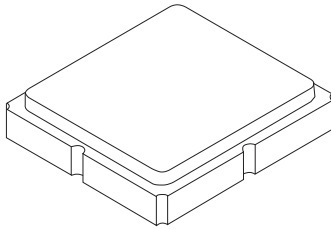


S22



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

Case and PCB Footprint Dimensions

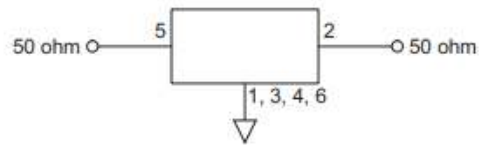
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-

Case Materials

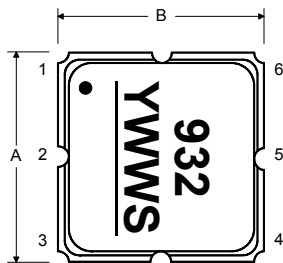
Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic

Electrical Connections

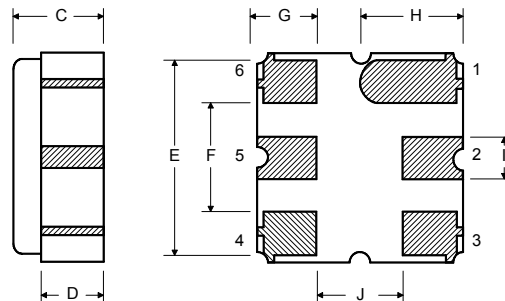
Connection	Terminals
Input	5
Output	2
Ground	All Others



TOP VIEW



BOTTOM VIEW



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

